



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-01-16
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPSC2006CW	HSLW*05DC1T6	A	3068	2017-01-16
Amount	UoM	Unit type	ST ECOPACK Grade	
4430.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	15.75-20.15-5.15	3	Through-hole	
Comment	TO 247			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 5th August 2016			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.93	Die / Leadframe	210
Lead	2.41	Soft solder	544

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	HSLW*05DC1T6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	5.019	mg	supplier	die	Silicium carbide	409-21-2		4.013	mg	799562	906
				supplier	metallization	Aluminium (Al)	7429-90-5		0.985	mg	196254	222
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	199	0
				supplier	back side metallization	Gold (Au)	7440-57-5		0.004	mg	797	1
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.016	mg	3188	4
Leadframe	Copper & its alloys	2826.184	mg	supplier	alloy	Copper (Cu)	7440-50-8		2821.522	mg	998350	636912
				supplier	alloy	Iron (Fe)	7439-89-6		1.300	mg	460	293
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		2.373	mg	840	536
				supplier	metallization	Nickel (Ni)	7440-02-0		0.915	mg	324	207
				supplier	metallization	Phosphorus (P)	12185-10-3		0.074	mg	26	17
Soft solder	Solder	2.525	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	2.411	mg	954851	544
				supplier	solder	Silver (Ag)	7440-22-4		0.063	mg	24950	14
				supplier	solder	Tin (Sn)	7440-31-5		0.051	mg	20199	12
Bonding wires	Other inorganic materials	2.339	mg	supplier	wire	Aluminium (Al)	7429-90-5		2.339	mg	1000000	528
Encapsulation	Other Organic Materials	1584.637	mg	supplier	mold compound	Silica, vitreous	60676-86-0		1378.634	mg	870000	311204
				supplier	mold compound	Epoxy resin	25068-38-6		158.464	mg	100000	35771
				supplier	mold compound	Phenol resin	29690-82-2		39.616	mg	25000	8943
				supplier	mold compound	Carbon Black	1333-86-4		7.923	mg	5000	1788
Connections coating	Solder	9.296	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		9.296	mg	1000000	2098